

## STM32WLE5xx, STM32WLE4xx device errata

### Applicability

This document applies to the part numbers of STM32WLE5xx, STM32WLE4xx devices and the device variants as stated in this page.

It gives a summary and a description of the device errata, with respect to the device datasheet and reference manual RM0461.

Deviation of the real device behavior from the intended device behavior is considered to be a device limitation. Deviation of the description in the reference manual or the datasheet from the intended device behavior is considered to be a documentation erratum. The term “*errata*” applies both to limitations and documentation errata.

**Table 1. Device summary**

Reference	Part numbers
STM32WLE5xx	STM32WLE5C8, STM32WLE5CB, STM32WLE5CC, STM32WLE5J8, STM32WLE5JB, STM32WLE5JC, STM32WLE5U8, STM32WLE5UB, STM32WLE5UC
STM32WLE4xx	STM32WLE4C8, STM32WLE4CB, STM32WLE4CC, STM32WLE4J8, STM32WLE4JB, STM32WLE4JC, STM32WLE4U8, STM32WLE4UB, STM32WLE4UC

**Table 2. Device variants**

Reference	Silicon revision codes	
	Device marking <sup>(1)</sup>	REV_ID <sup>(2)</sup>
STM32WLE5xx, STM32WLE4xx	Z	0x1001
	Y	0x1002

1. Refer to the device datasheet for how to identify this code on different types of package.
2. REV\_ID[15:0] bitfield of DBGMCU\_IDCODER register.

# 1 Summary of device errata

The following table gives a quick reference to the STM32WLE5xx, STM32WLE4xx device limitations and their status:

A = workaround available

N = no workaround available

P = partial workaround available

Applicability of a workaround may depend on specific conditions of target application. Adoption of a workaround may cause restrictions to target application. Workaround for a limitation is deemed partial if it only reduces the rate of occurrence and/or consequences of the limitation, or if it is fully effective for only a subset of instances on the device or in only a subset of operating modes, of the function concerned.

**Table 3. Summary of device limitations**

Function	Section	Limitation	Status	
			Rev. Z	Rev. Y
Core	2.1.1	Interrupted loads to SP can cause erroneous behavior	A	A
	2.1.2	Store immediate overlapping exception return operation might vector to incorrect interrupt	A	A
System	2.2.1	Wrong DMAMUX synchronization and trigger input connections to EXTI	A	-
	2.2.2	Overwriting with all zeros a Flash memory location previously programmed with all ones fails	N	N
	2.2.3	Option byte loading failure at high MSI system clock frequency	A	-
	2.2.4	A system reset occurs when nRST_SHDW is set and nRST_STDBY is cleared and Shutdown mode is entered	A	-
	2.2.5	FLASH_ECCR corrupted upon reset or power-down occurring during Flash memory program or erase operation	A	A
	2.2.6	Voltage drop on the 1.2 V regulated supply when switching MSI to 48 MHz	A	A
	2.2.7	Sensitivity affected by HSE activation in high bandwidth channel	A	-
	2.2.8	Sensitivity degradation in LNA boosted mode	A	A
	2.2.9	SysTick trigger in debug emulation generates HardFault	A	A
	2.2.10	Debug HALT command in debug emulation generates HardFault	A	-
	2.2.11	Potential deadlock condition on wakeup from a lower-power mode	A	-
	2.2.12	JTAG cannot be used without the JTAG NRST pin	N	-
	2.2.13	Flash PCROP is not operating properly	N	-
	2.2.14	TX spurs around carrier at a multiple of HSE clock frequency	A	A
TIM	2.3.1	One-pulse mode trigger not detected in master-slave reset + trigger configuration	P	P
	2.3.2	Consecutive compare event missed in specific conditions	N	N
	2.3.3	Output compare clear not working with external counter reset	P	P
LPTIM	2.4.1	Device may remain stuck in LPTIM interrupt when entering Stop mode	A	A
	2.4.2	ARRM and CMPM flags are not set when APB clock is slower than kernel clock	P	P
	2.4.3	Device may remain stuck in LPTIM interrupt when clearing event flag	P	P
RTC and TAMP	2.5.1	Alarm flag may be repeatedly set when the core is stopped in debug	N	N

Function	Section	Limitation	Status	
			Rev. Z	Rev. Y
RTC and TAMP	2.5.2	A tamper event fails to trigger timestamp or timestamp overflow events during a few cycles after clearing TSF	N	N
	2.5.3	REFCKON write protection associated to INIT KEY instead of CAL KEY	A	A
	2.5.4	Tamper flag not set on LSE failure detection	N	N
	2.5.5	Binary mode: SSR is not reloaded with 0xFFFF FFFF when SSCLR = 1	A	A
I2C	2.6.1	Wrong data sampling when data setup time (tSU;DAT) is shorter than one I2C kernel clock period	P	P
	2.6.2	Spurious bus error detection in master mode	A	A
	2.6.3	OVR flag not set in underrun condition	N	N
	2.6.4	Transmission stalled after first byte transfer	A	A
USART	2.7.1	Anticipated end-of-transmission signaling in SPI slave mode	A	A
	2.7.2	Data corruption due to noisy receive line	N	N
	2.7.3	DMA stream locked when transferring data to/from USART	A	A

## 2 Description of device errata

The following sections describe limitations of the applicable devices with Arm® core and provide workarounds if available. They are grouped by device functions.

*Note:* Arm is a registered trademark of Arm Limited (or its subsidiaries) in the US and/or elsewhere.



### 2.1 Core

Reference manual and errata notice for the Arm® Cortex®-M4 FPU core revision r0p1 is available from <http://infocenter.arm.com>.

#### 2.1.1 Interrupted loads to SP can cause erroneous behavior

This limitation is registered under Arm ID number 752770 and classified into “Category B”. Its impact to the device is minor.

##### Description

If an interrupt occurs during the data-phase of a single word load to the stack-pointer (SP/R13), erroneous behavior can occur. In all cases, returning from the interrupt will result in the load instruction being executed an additional time. For all instructions performing an update to the base register, the base register will be erroneously updated on each execution, resulting in the stack-pointer being loaded from an incorrect memory location.

The affected instructions that can result in the load transaction being repeated are:

- LDR SP, [Rn],#imm
- LDR SP, [Rn,#imm]!
- LDR SP, [Rn,#imm]
- LDR SP, [Rn]
- LDR SP, [Rn,Rm]

The affected instructions that can result in the stack-pointer being loaded from an incorrect memory address are:

- LDR SP,[Rn],#imm
- LDR SP,[Rn,#imm]!

As compilers do not generate these particular instructions, the limitation is only likely to occur with hand-written assembly code.

##### Workaround

Both issues may be worked around by replacing the direct load to the stack-pointer, with an intermediate load to a general-purpose register followed by a move to the stack-pointer.

#### 2.1.2 Store immediate overlapping exception return operation might vector to incorrect interrupt

This limitation is registered under Arm ID number 838869 and classified into “Category B (rare)”. Its impact to the device is minor.

##### Description

The core includes a write buffer that permits execution to continue while a store is waiting on the bus. Under specific timing conditions, during an exception return while this buffer is still in use by a store instruction, a late change in selection of the next interrupt to be taken might result in there being a mismatch between the interrupt acknowledged by the interrupt controller and the vector fetched by the processor.

The failure occurs when the following condition is met:

1. The handler for interrupt A is being executed.
2. Interrupt B, of the same or lower priority than interrupt A, is pending.
3. A store with immediate offset instruction is executed to a bufferable location.
  - STR/STRH/STRB <Rt>, [<Rn>,#imm]
  - STR/STRH/STRB <Rt>, [<Rn>,#imm]!
  - STR/STRH/STRB <Rt>, [<Rn>],#imm
4. Any number of additional data-processing instructions can be executed.
5. A BX instruction is executed that causes an exception return.
6. The store data has wait states applied to it such that the data is accepted at least two cycles after the BX is executed.
  - Minimally, this is two cycles if the store and the BX instruction have no additional instructions between them.
  - The number of wait states required to observe this erratum needs to be increased by the number of cycles between the store and the interrupt service routine exit instruction.
7. Before the bus accepts the buffered store data, another interrupt C is asserted which has the same or lower priority as A, but a greater priority than B.

Example:

The processor should execute interrupt handler C, and on completion of handler C should execute the handler for B. If the conditions above are met, then this erratum results in the processor erroneously clearing the pending state of interrupt C, and then executing the handler for B twice. The first time the handler for B is executed it will be at interrupt C's priority level. If interrupt C is pending by a level-based interrupt which is cleared by C's handler then interrupt C will be pending again once the handler for B has completed and the handler for C will be executed.

As the STM32 interrupt C is level based, it eventually becomes pending again and is subsequently handled.

### Workaround

For software not using the memory protection unit, this erratum can be worked around by setting DISDEFWBUF in the Auxiliary Control Register.

In all other cases, the erratum can be avoided by ensuring a DSB occurs between the store and the BX instruction. For exception handlers written in C, this can be achieved by inserting the appropriate set of intrinsics or inline assembly just before the end of the interrupt function, for example:

ARMCC:

```
...
__schedule_barrier();
asm{DSB};
__schedule_barrier();
}
```

GCC:

```
...
asm volatile ("dsb 0xf":::"memory");
}
```

## 2.2 System

### 2.2.1 Wrong DMAMUX synchronization and trigger input connections to EXTI

#### Description

By error, synchronization and trigger inputs of the DMAMUX peripheral are connected to interrupt output lines of the EXTI block, instead of being connected to its SYSCFG multiplexer output lines.

The EXTI interrupt lines exhibit a rising-edge transition upon each active transition (rising, falling or both) of corresponding GPIOs, as defined in the EXTI\_RTSTRx and EXTI\_FTSRr registers.

As a consequence, the falling active edge option of the DMAMUX synchronization and trigger inputs is unusable because falling edges on these inputs do not occur upon GPIO events but upon clearing the EXTI interrupt pending flags (by setting the corresponding PIF bits of the EXTI\_PRR register).

#### Workaround

For the DMAMUX synchronization and trigger events to occur upon determined rising or/and falling edge of the corresponding GPIOs:

- Set the desired active edge polarities of the corresponding GPIOs through the EXTI\_RTSTRx and EXTI\_FTSRr registers.
- Set the active edge polarity to rising for all corresponding DMAMUX input lines, through the SPOL bits of the DMAMUX\_CxCR register (for synchronization inputs) and the GPOL bits of the DMAMUX\_RGxCR register (for trigger inputs).
- Ensure that EXTI interrupt pending flags corresponding to the GPIOs used for DMAMUX inputs are cleared in the EXTI interrupt service routine.

*Note:* This can be ensured if using the `HAL_GPIO_IrqHandler` function provided by STMicroelectronics.

### 2.2.2 Overwriting with all zeros a Flash memory location previously programmed with all ones fails

#### Description

Any attempt to re-program with all zeros (0x0000 0000 0000 0000) a Flash memory location previously programmed with 0xFFFF FFFF FFFF FFFF fails and the PROGERR flag of the FLASH\_SR register is set.

#### Workaround

None.

### 2.2.3 Option byte loading failure at high MSI system clock frequency

#### Description

The option bytes are not loaded correctly upon setting the OBL\_LAUNCH bit of the FLASH\_CR register when the frequency of MSI oscillator used as system clock source is higher than 16 MHz.

#### Workaround

Before loading the option bytes by setting the OBL\_LAUNCH bit of the FLASH\_CR register, either change the system clock source to other than MSI oscillator, or set the MSI clock frequency to less than 16 MHz.

### 2.2.4 A system reset occurs when nRST\_SHDW is set and nRST\_STDBY is cleared and Shutdown mode is entered

#### Description

When the following configuration is selected:

- nRST\_SHDW is set
- nRST\_STDBY is cleared,

a system reset is generated when Shutdown mode is entered.

#### Workaround

The only valid configuration to avoid a reset after entering into Shutdown mode is the following:

- nRST\_SHDW is set
- nRST\_STDBY is set.

### 2.2.5 FLASH\_ECCR corrupted upon reset or power-down occurring during Flash memory program or erase operation

#### Description

Reset or power-down occurring during a Flash memory location program or erase operation, followed by a read of the same memory location, may lead to a corruption of the FLASH\_ECCR register content.

#### Workaround

Under such condition, erase the page(s) corresponding to the Flash memory location.

### 2.2.6 Voltage drop on the 1.2 V regulated supply when switching MSI to 48 MHz

#### Description

A voltage drop to 1.08 V may occur on the 1.2 V regulated supply when the MSI frequency is changed as follows:

- from MSI at 400 kHz to MSI at 24 MHz and above
- from MSI at 1 MHz to MSI at 48 MHz

As a result, the voltage drop may cause CPU HardFault.

#### Workaround

To ensure there is no impact on the 1.2 V supply, introduce an intermediate MSI frequency change step as follows:

- Change the MSI frequency range from 400 kHz to 12 MHz, then to 24 MHz and above, as illustrated in these examples:
  - MSI@400 kHz → MSI@12 MHz → MSI@24 MHz
  - MSI@400 kHz → MSI@12 MHz → MSI@48 MHz.
- Change the MSI frequency range from 1 MHz to 12 MHz, then to 48 MHz, as illustrated in this example: MSI@400 kHz → MSI@12 MHz → MSI@48 MHz.

### 2.2.7 Sensitivity affected by HSE activation in high bandwidth channel

#### Description

The sensitivity of the high bandwidth channels (HB) EU864 and US928 is affected when HSE is used as system clock. HSE cannot be used as system clock when channels EU864 or US928 are used. Except if the LoRa<sup>®</sup> modulation is needed, the user can also replace 32 MHz HSE clock by 31.25 MHz HSE clock.

#### Workaround

Use a different clock source for the system, for example MSI or HSI with or without PLL.

### 2.2.8 Sensitivity degradation in LNA boosted mode

#### Description

Reduced performance is observed in some specific LNA boost mode use cases. There is a potential loss of sensitivity of approximately up to 1.5 dB on rev Z and 0.75 dB in rev Y, versus specification for LoRa<sup>®</sup> and GFSK modulation at 915 MHz.

#### Workaround

None.

### 2.2.9 SysTick trigger in debug emulation generates HardFault

#### Description

When the CPU enters its deepsleep state and debug emulation is active, the CPU SysTick is still running and able to trigger interrupts. The CPU is woken up and fetches code from the system Flash memory. As the Flash memory is not active, the CPU starts fetching code from a resource that is not available, and receives random data from the bus, causing HardFault.

When the debug emulation is active and the CPU enters its deepsleep state, the system exhibits unpredictable behavior due to the SysTick activity.

#### Workaround

Always disable SysTick before the CPU enters its deepsleep state. This consistently prevents any interrupt triggering and any possibility of HardFault.

### 2.2.10 Debug HALT command in debug emulation generates HardFault

#### Description

When the CPU is in deepsleep state with active debug emulation and a *debug HALT - debug RUN* command sequence is submitted, the CPU wakes up and starts fetching data from Flash memory. As Flash memory is unavailable, the CPU receives random data from the bus which causes HardFault.

Debug cannot be performed on the system when the CPU is in deepsleep state and debug emulation is active.

#### Workaround

Change the debug sequence to perform a detach/attach procedure before any "HALT/RUN". Also enable the CDBGPWRUP wakeup on the AIEC before the CPU goes in deepsleep state.

### 2.2.11 Potential deadlock condition on wakeup from a lower-power mode

#### Description

Following multiple wakeups from Stop 1, Stop 2 or Standby, the power supply management block may not restart properly. This occurs on a specific timing of the wakeup event and Run duration.

The issue may occur in the event of an asynchronous wakeup when the MCU remains in Run for less than 60  $\mu$ s after a wakeup.

When this issue happens, the power consumption in Run mode does not correspond to the datasheet. The global power consumption is not impacted.

#### Workaround

If it is key to control accurately the power consumption, use one of the following measures:

- General workaround (valid also if SMPS is used before entering wakeup): wait for the LDO to reach a stable condition before entering a low-power mode.  
A software implementation solution is to check that the LDORDY bit of the PWR\_SR2 register is set before entering a low-power mode.
- LDO use case only (SMPS was not used before entering wakeup): the deadlock condition, which can potentially occur at wakeup from a low-power mode, can be solved by generating a pulse on the SMPSEN bit of the PWR\_CR5 register controlling the SMPS activation.  
A software implementation solution is to toggle the SMPSEN bit of the PWR\_CR5 register at each wakeup from low-power mode.



### 2.2.12 JTAG cannot be used without the JTAG NRST pin

#### Description

When CPU1 is in deepsleep state with active debug emulation and CPU2 is stopped as well, and a *debug HALT* - *debug RUN* command sequence is submitted, CPU1 wakes up and starts to fetch from Flash memory. In this condition, the Flash memory is off, CPU1 retrieves random information from the bus which causes a HardFault.

By default after reset, PB4 is configured as alternate function for JTAG NRESET function. If this pin is reused in another configuration (GPIO, analog or alternate function for another function), the product JTAG NRESET internal signal is forced to 0.

#### Workaround

None.

### 2.2.13 Flash PCROP is not operating properly

#### Description

The PCROP protection on the Flash memory area does not work as expected.

#### Workaround

None.

### 2.2.14 TX spurs around carrier at a multiple of HSE clock frequency

#### Description

Unwanted spurs may occur around the transmission carrier with frequency that is an integer multiple of the HSE clock frequency. For example, around 480 MHz or 864 MHz if the HSE clock frequency is 32 MHz.

#### Workaround

Apply one of the following measures:

- Choose the HSE clock frequency so that its integer multiples are at least 1.5 MHz away from the desired transmission carrier frequency.
- Do not use transmission channels within the range of  $\pm 1.5$  MHz around carrier frequencies that are integer multiples of the HSE clock frequency.

*Note:* The first measure cannot be applied if the application requires LoRa<sup>®</sup> modulation that imposes the use of 32 MHz HSE clock.

## 2.3 TIM

### 2.3.1 One-pulse mode trigger not detected in master-slave reset + trigger configuration

#### Description

The failure occurs when several timers configured in one-pulse mode are cascaded, and the master timer is configured in combined reset + trigger mode with the MSM bit set:

OPM = 1 in TIMx\_CR1, SMS[3:0] = 1000 and MSM = 1 in TIMx\_SMCR.

The MSM delays the reaction of the master timer to the trigger event, so as to have the slave timers cycle-accurately synchronized.

If the trigger arrives when the counter value is equal to the period value set in the TIMx\_ARR register, the one-pulse mode of the master timer does not work and no pulse is generated on the output.

### Workaround

None. However, unless a cycle-level synchronization is mandatory, it is advised to keep the MSM bit reset, in which case the problem is not present. The MSM = 0 configuration also allows decreasing the timer latency to external trigger events.

## 2.3.2 Consecutive compare event missed in specific conditions

### Description

Every match of the counter (CNT) value with the compare register (CCR) value is expected to trigger a compare event. However, if such matches occur in two consecutive counter clock cycles (as consequence of the CCR value change between the two cycles), the second compare event is missed for the following CCR value changes:

- in edge-aligned mode, from ARR to 0:
  - first compare event: CNT = CCR = ARR
  - second (missed) compare event: CNT = CCR = 0
- in center-aligned mode while up-counting, from ARR-1 to ARR (possibly a new ARR value if the period is also changed) at the crest (that is, when TIMx\_RCR = 0):
  - first compare event: CNT = CCR = (ARR-1)
  - second (missed) compare event: CNT = CCR = ARR
- in center-aligned mode while down-counting, from 1 to 0 at the valley (that is, when TIMx\_RCR = 0):
  - first compare event: CNT = CCR = 1
  - second (missed) compare event: CNT = CCR = 0

This typically corresponds to an abrupt change of compare value aiming at creating a timer clock single-cycle-wide pulse in toggle mode.

As a consequence:

- In toggle mode, the output only toggles once per counter period (squared waveform), whereas it is expected to toggle twice within two consecutive counter cycles (and so exhibit a short pulse per counter period).
- In center mode, the compare interrupt flag does not rise and the interrupt is not generated.

*Note:* The timer output operates as expected in modes other than the toggle mode.

### Workaround

None.

## 2.3.3 Output compare clear not working with external counter reset

### Description

The output compare clear event (ocref\_clr) is not correctly generated when the timer is configured in the following slave modes: Reset mode, Combined reset + trigger mode, and Combined gated + reset mode.

The PWM output remains inactive during one extra PWM cycle if the following sequence occurs:

1. The output is cleared by the ocref\_clr event.
2. The timer reset occurs before the programmed compare event.

### Workaround

Apply one of the following measures:

- Use BKIN (or BKIN2 if available) input for clearing the output, selecting the Automatic output enable mode (AOE = 1).
- Mask the timer reset during the PWM ON time to prevent it from occurring before the compare event (for example with a spare timer compare channel open-drain output connected with the reset signal, pulling the timer reset line down).

## 2.4 LPTIM

### 2.4.1 Device may remain stuck in LPTIM interrupt when entering Stop mode

#### Description

This limitation occurs when disabling the low-power timer (LPTIM).

When the user application clears the ENABLE bit in the LPTIM\_CR register within a small time window around one LPTIM interrupt occurrence, then the LPTIM interrupt signal used to wake up the device from Stop mode may be frozen in active state. Consequently, when trying to enter Stop mode, this limitation prevents the device from entering low-power mode and the firmware remains stuck in the LPTIM interrupt routine.

This limitation applies to all Stop modes and to all instances of the LPTIM. Note that the occurrence of this issue is very low.

#### Workaround

In order to disable a low power timer (LPTIMx) peripheral, do not clear its ENABLE bit in its respective LPTIM\_CR register. Instead, reset the whole LPTIMx peripheral via the RCC controller by setting and resetting its respective LPTIMxRST bit in RCC\_APBxRSTRz register.

### 2.4.2 ARR and CMPM flags are not set when APB clock is slower than kernel clock

#### Description

When LPTIM is configured in one shot mode and APB clock is lower than kernel clock, there is a chance that ARR and CMPM flags are not set at the end of the counting cycle defined by the repetition value REP[7:0]. This issue can only occur when the repetition counter is configured with an odd repetition value.

#### Workaround

To avoid this issue the following formula must be respected:

$$\{ARR, CMP\} \geq KER\_CLK / (2 * APB\_CLK),$$

where APB\_CLK is the LPTIM APB clock frequency, and KER\_CLK is the LPTIM kernel clock frequency. ARR and CMP are expressed in decimal value.

**Example:** The following example illustrates a configuration where the issue can occur:

- APB clock source (MSI) = 1 MHz , Kernel clock source (HSI) = 16 MHz
- Repetition counter is set with REP[7:0] = 0x3 (odd value)

The above example is subject to issue, unless the user respects:

$$\{CMP, ARR\} \geq 16 \text{ MHz} / (2 * 1 \text{ MHz})$$

→ ARR must be  $\geq 8$  and CMP must be  $\geq 8$

*Note:* REP set to 0x3 means that effective repetition is REP+1 (= 4) but the user must consider the parity of the value loaded in LPTIM\_RCR register (=3, odd) to assess the risk of issue.

### 2.4.3 Device may remain stuck in LPTIM interrupt when clearing event flag

#### Description

This limitation occurs when the LPTIM is configured in interrupt mode (at least one interrupt is enabled) and the software clears any flag in LPTIM\_ISR register by writing its corresponding bit in LPTIM\_ICR register. If the interrupt status flag corresponding to a disabled interrupt is cleared simultaneously with a new event detection, the set and clear commands might reach the APB domain at the same time, leading to an asynchronous interrupt signal permanently stuck high.

This issue can occur either during an interrupt subroutine execution (where the flag clearing is usually done), or outside an interrupt subroutine.

Consequently, the firmware remains stuck in the LPTIM interrupt routine, and the device cannot enter Stop mode.

### Workaround

To avoid this issue, it is strongly advised to follow the recommendations listed below:

- Clear the flag only when its corresponding interrupt is enabled in the interrupt enable register.
- If for specific reasons, it is required to clear some flags that have corresponding interrupt lines disabled in the interrupt enable register, it is recommended to clear them during the current subroutine prior to those which have corresponding interrupt line enabled in the interrupt enable register.
- Flags must not be cleared outside the interrupt subroutine.

*Note:* The proper clear sequence is already implemented in the `HAL_LPTIM_IRQHandler` in the `STM32Cube`.

## 2.5 RTC and TAMP

### 2.5.1 Alarm flag may be repeatedly set when the core is stopped in debug

#### Description

When the core is stopped in debug mode, the clock is supplied to subsecond RTC alarm downcounter even though the device is configured to stop the RTC in debug.

As a consequence, when the subsecond counter is used for alarm condition (the `MASKSS[3:0]` bitfield of the `RTC_ALRMASR` and/or `RTC_ALRMBSSR` register set to a non-zero value) and the alarm condition is met just before entering a breakpoint or `printf`, the `ALRAF` and/or `ALRBF` flag of the `RTC_SR` register is repeatedly set by hardware during the breakpoint or `printf`, which makes any tentative to clear the flag(s) ineffective.

#### Workaround

None.

### 2.5.2 A tamper event fails to trigger timestamp or timestamp overflow events during a few cycles after clearing TSF

#### Description

With the timestamp on tamper event enabled (`TAMPTS` bit of the `RTC_CR` register set), a tamper event is ignored if it occurs:

- within four APB clock cycles after setting the `CTSF` bit of the `RTC_SCR` register to clear the `TSF` flag, while the `TSF` flag is not yet effectively cleared (it fails to set the `TSOVF` flag)
- within two `ck_apre` cycles after setting the `CTSF` bit of the `RTC_SCR` register to clear the `TSF` flag, when the `TSF` flag is effectively cleared (it fails to set the `TSF` flag and timestamp the calendar registers)

#### Workaround

None.

### 2.5.3 REFCKON write protection associated to INIT KEY instead of CAL KEY

#### Description

The write protection of the `REFCKON` bit is unlocked if the key sequence is written in `RTC_WPR` with the privilege and security rights set by the `INITPRIV` and `INITSEC` bits, instead of being set by the `CALPRIV` and `CALSEC` bits.

#### Workaround

Unlock the `INIT KEY` before writing `REFCKON`.

## 2.5.4 Tamper flag not set on LSE failure detection

### Description

With the timestamp on tamper event enabled (the TAMPTS bit of the RTC\_CR register set), the LSE failure detection (LSE clock stopped) event connected to the internal tamper 3 fails to raise the ITAMP3F and ITAMP3MF flags, although it duly erases or blocks (depending on the internal tamper 3 configuration) the backup registers and other device secrets, and the RTC and TAMP peripherals resume normally upon the LSE restart.

*Note: As expected in this particular case, the TSF and TSMF flags remain low as long as LSE is stopped as they require running RTCCLK clock to operate.*

### Workaround

None.

## 2.5.5 Binary mode: SSR is not reloaded with 0xFFFF FFFF when SSCLR = 1

### Description

When SSCLR bit of the RTC\_ALRMxSSR register is set when in binary mode, SSR is reloaded with 0xFFFF FFFF at the end of the ck\_apre cycle when RTC\_SSR is set to RTC\_ALRxBINR (x stands for either A or B)

RTC\_SSR is not reloaded with 0xFFFF FFFF if RTC\_ALRxBINR is modified while RTC\_SSR is set to RTC\_ALRxBINR. Rather, SSR continues to decrement.

### Workaround

The workarounds are described for alarm A, and can be applied in the same manner for alarm B. Two workarounds are proposed, the second one requires to use the second alarm.

- Wait for one ck\_apre cycle after an alarm A event before changing the RTC\_ALRABINR register value.
- Do not reprogram RTC\_ALRABINR following the alarm A event itself. Instead, use alarm B configured with RTC\_ALRBBINR set to 0xFFFF FFFF, and reprogram RTC\_ALRABINR after the alarm B event. This ensures that one ck\_apre cycle elapses following the alarm A event.

## 2.6 I2C

### 2.6.1 Wrong data sampling when data setup time ( $t_{\text{SU;DAT}}$ ) is shorter than one I2C kernel clock period

#### Description

The I<sup>2</sup>C-bus specification and user manual specify a minimum data setup time ( $t_{\text{SU;DAT}}$ ) as:

- 250 ns in Standard mode
- 100 ns in Fast mode
- 50 ns in Fast mode Plus

The device does not correctly sample the I<sup>2</sup>C-bus SDA line when  $t_{\text{SU;DAT}}$  is smaller than one I2C kernel clock (I<sup>2</sup>C-bus peripheral clock) period: the previous SDA value is sampled instead of the current one. This can result in a wrong receipt of slave address, data byte, or acknowledge bit.

### Workaround

Increase the I2C kernel clock frequency to get I2C kernel clock period within the transmitter minimum data setup time. Alternatively, increase transmitter's minimum data setup time. If the transmitter setup time minimum value corresponds to the minimum value provided in the I<sup>2</sup>C-bus standard, the minimum I2CCLK frequencies are as follows:

- In Standard mode, if the transmitter minimum setup time is 250 ns, the I2CCLK frequency must be at least 4 MHz.
- In Fast mode, if the transmitter minimum setup time is 100 ns, the I2CCLK frequency must be at least 10 MHz.
- In Fast-mode Plus, if the transmitter minimum setup time is 50 ns, the I2CCLK frequency must be at least 20 MHz.

## 2.6.2 Spurious bus error detection in master mode

### Description

In master mode, a bus error can be detected spuriously, with the consequence of setting the BERR flag of the I2C\_SR register and generating bus error interrupt if such interrupt is enabled. Detection of bus error has no effect on the I<sup>2</sup>C-bus transfer in master mode and any such transfer continues normally.

### Workaround

If a bus error interrupt is generated in master mode, the BERR flag must be cleared by software. No other action is required and the ongoing transfer can be handled normally.

## 2.6.3 OVR flag not set in underrun condition

### Description

In slave transmission with clock stretching disabled (NOSTRETCH = 1 in the I2C\_CR1 register), an underrun condition occurs if the current byte transmission is completed on the I2C bus, and the next data is not yet written in the TXDATA[7:0] bitfield. In this condition, the device is expected to set the OVR flag of the I2C\_ISR register and send 0xFF on the bus.

However, if the I2C\_TXDR is written within the interval between two I2C kernel clock cycles before and three APB clock cycles after the start of the next data transmission, the OVR flag is not set, although the transmitted value is 0xFF.

### Workaround

None.

## 2.6.4 Transmission stalled after first byte transfer

### Description

When the first byte to transmit is not prepared in the TXDATA register, two bytes are required successively, through TXIS status flag setting or through a DMA request. If the first of the two bytes is written in the I2C\_TXDR register in less than two I2C kernel clock cycles after the TXIS/DMA request, and the ratio between APB clock and I2C kernel clock frequencies is between 1.5 and 3, the second byte written in the I2C\_TXDR is not internally detected. This causes a state in which the I2C peripheral is stalled in master mode or in slave mode, with clock stretching enabled (NOSTRETCH = 0). This state can only be released by disabling the peripheral (PE = 0) or by resetting it.

### Workaround

Apply one of the following measures:

- Write the first data in I2C\_TXDR before the transmission starts.
- Set the APB clock frequency so that its ratio with respect to the I2C kernel clock frequency is lower than 1.5 or higher than 3.

## 2.7 USART

### 2.7.1 Anticipated end-of-transmission signaling in SPI slave mode

#### Description

In SPI slave mode, at low USART baud rate with respect to the USART kernel and APB clock frequencies, the *transmission complete* flag TC of the USARTx\_ISR register may unduly be set before the last bit is shifted on the transmit line.

This leads to data corruption if, based on this anticipated end-of-transmission signaling, the application disables the peripheral before the last bit is transmitted.

#### Workaround

Upon the TC flag rise, wait until the clock line remains idle for more than the half of the communication clock cycle. Then only consider the transmission as ended.

### 2.7.2 Data corruption due to noisy receive line

#### Description

In UART mode with oversampling by 8 or 16 and with 1 or 2 stop bits, the received data may be corrupted if a glitch to zero shorter than the half-bit occurs on the receive line within the second half of the stop bit.

#### Workaround

None.

### 2.7.3 DMA stream locked when transferring data to/from USART

#### Description

When a USART is issuing a DMA request to transfer data, if a concurrent transfer occurs, the requested transfer may not be served and the DMA stream may stay locked.

#### Workaround

Use the alternative peripheral DMA channel protocol by setting bit 20 of the DMA\_SxCR register.

This bit is reserved in the documentation and must be used only on the stream that manages data transfers for USART peripherals.

## Revision history

**Table 4. Document revision history**

Date	Version	Changes
06-Nov-2020	1	Initial release.
21-Apr-2021	2	Added: <ul style="list-style-type: none"> <li>• JTAG cannot be used without the JTAG NRST pin</li> <li>• Flash PCROP is not operating properly</li> <li>• TX spurs around carrier at a multiple of HSE clock frequency</li> <li>• Binary mode: SSR is not reloaded with 0xFFFF FFFF when SSCLR = 1</li> <li>• die revision Y</li> </ul> Updated: <ul style="list-style-type: none"> <li>• Sensitivity affected by HSE activation in high bandwidth channel</li> <li>• Sensitivity degradation in LNA boosted mode</li> <li>• Potential deadlock condition on wakeup from a lower-power mode</li> </ul> Removed <i>VDIV or VSQRT instructions might not complete correctly when very short ISRs are used in Core.</i>



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